



Space Level Screening



Nano D



Micro-D



Micro and Nano Strips

Ordering Steps:

Step 1 - Choose a suitable Micro or Nano connector

Step 2 - Choose a level of Space Screening

Level 1 - Mission Critical (Highest Reliability)

Level 2 - High Reliability

Level 3 - Standard Reliability

Step 3 - Select any added outgassing processing needed.

Step 4 - Specify chosen ORDERING CODES from table below.

These codes should be used as separate line items on all quote Requests and Purchase Orders as required.

Ordering Codes: (Quoted as separate line items)

Screening Level	Special Screening Only	Processing for Outgassing
Level 1 - Mission Critical	SPT1	All standard materials exhibit less than 1.0% TML without additional processing. Contact service for special requirements.
Level 2 - High Reliability	SPT2	
Level 3 - Standard Reliability	Standard	

	Micro (.050" Center)		Nano (.025" Center)	
	Sample Size(Allowable Failures)			
Inspection/Test	Level 1 Com'I/SCD	Level 2 Com'I/SCD	Level 1 Com'I/SCD	Level 2 Com'I/SCD
Visual	100%	100%	100%	100%
Mechanical	2 (0)	2 (0)	2 (0)	2 (0)
Voltage Rating (DWV)	100%	2 (0)	100%	2 (0)
Insulation Resistance	2 (0)	2 (0)	100%	100%
Temperature Cycling	2 (0)	2 (0)	2 (0)	-
Low Level Contact Resistance	2 (0)	2 (0)	2 (0)	2 (0)
Mating/Unmating Force	2 (0)	-	2 (0)	-
Solderability/Resistance to heat (SMT & Thru-Hole only)	2 (0)	-	2 (0)	-
Note: NASA screening requirements from Table 2C & 2J of EEE-INST-002				

Nano - Rectangular Design @ .025" Pitch

- Materials: For up to +200°C operation*
- Insulator: 2 Row-LCP / 30% glass, 1 Row-PPS / 40% glass, Low Outgassing meets NASA SP-R0022
- Pin count: @ .025" pitch - up to 60 positions
- Single row or 2 Row
- Board Mounting: SMT or Thru-Hole
- Current Rating: Up to 1 amp
- Shock & Vibration: Exceeds MIL-DTL-32139
- High Shock Mounting & Mating Hardware

Micro - Rectangular Design @ .050" Pitch

- Materials: For up to +200°C operation*
- Insulator: PPS / 40% glass, Low Outgassing meets NASA SP-R0022
- Pin count: @ .050" pitch – up to 97 positions
- Single row or dual row
- Board Mounting: SMT or Thru-Hole
- Current Rating: Up to 3 amp
- Shock & Vibration: Exceeds MIL-DTL-32139
- High Shock Mounting & Mating Hardware
- Micro - Rectangular Design @ .050" Pitch

Metal Circular Connector Series

- Outgassing meets NASA SP-R-0022
- Threaded Coupline Mate - Unmate
- EMI Cable Shield to Shell Design
- Pin Count Micro - Up to 27 Positions
- Pin Count Nano - Up to 28 positions
- O-ring Sealed
- High-Flex Cable for rotating systems

New Connector Design & Materials are focused on low weight, high density and rugged superiority to meet the extreme reliability demands during launch through deep space operations. Special “rugged-mount” designs can be made to system configurations. Materials have been selected for thermal-expansion match to sustain continued performance from launch pad through geo-thermal orbit conditions. With increased densification of cable diameter and reduced connector size, nano-interconnect systems offer significantly reduced weight and lower payload costs. Our design team will also help with unique cable requirements to solve EMI, Cross-talk and High Speed problems. Backshells, Strain-reliefs, Braided shields and Special cables are all available to improve handling and extend life in your system. Call our Sales Rep or Omnetics direct and we will work with you to optimize your design.

* **High Temperature Epoxy available upon request**